

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6317019

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
PENGFEI WU	07/26/2018
STEPHEN J. TODD	08/12/2018
KUN WANG	07/27/2018
RECEIVING PARTY DATA	
Name:	EMC IP HOLDING COMPANY LLC
Street Address:	176 SOUTH STREET
City:	HOPKINTON
State/Country:	MASSACHUSETTS
Postal Code:	01748
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17031282
CORRESPONDENCE DATA	
Fax Number:	(631)393-6271
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(631)393-6270
Email:	nyoffice@rml-law.com
Correspondent Name:	WILLIAM E. LEWIS
Address Line 1:	48 SOUTH SERVICE ROAD, SUITE 100
Address Line 2:	RYAN, MASON & LEWIS, LLP
Address Line 4:	MELVILLE, UNITED STATES 11747
ATTORNEY DOCKET NUMBER:	111731.02
NAME OF SUBMITTER:	WILLIAM E. LEWIS
SIGNATURE:	/William E. Lewis/
DATE SIGNED:	09/24/2020
Total Attachments: 10	
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ASSIGNMENT

WHEREAS, we, Pengfei Wu, Stephen J. Todd and Kun Wang, have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled **DECENTRALIZED POLICY PUBLISH AND QUERY SYSTEM FOR MULTI-CLOUD COMPUTING ENVIRONMENT**, the specification of which:

☒ [X] is being executed on even date herewith and is about to be filed in the United States Patent Office;

☐ [] was filed on _____ as U.S. Application No. _____;

☐ [] was patented under U.S. Patent No. _____ on _____.

WHEREAS, EMC IP Holding Company LLC (hereinafter "ASSIGNEE"), a limited liability company organized and existing under the laws of the State of Delaware and having a usual place of business at 176 South Street, Hopkinton, Massachusetts 01748 desires to acquire an interest therein in accordance with agreements duly entered into with us;

NOW, THEREFORE, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by us had this assignment and sale not been made; we hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. We hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

AND, we hereby further agree for ourselves and our executors and administrators to execute upon request any other lawful documents and likewise to perform any other lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of substitution,

reissue, divisional or continuation applications and preliminary or other statements and the giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

AND, we do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives.

IN TESTIMONY WHEREOF, we have hereunto set our hands and affixed our seals as set forth below:

Date: 2018/7/26

Pengfei Wu
Inventor's Signature

Print full name of first inventor: Pengfei Wu
Residence: Shanghai, China
Citizenship: China
Mailing Address: 5th Floor, 1st Building, KIC Plaza, No. 252
Songhu Road, Yangpu District
Shanghai, China 200433

I Yao Ye lin (name) whose residential address is

5th Floor, 1st Building, KIC Plaza, No. 252 Songhu Road, Shanghai, China
was personally present and did see Pengfei Wu (name of person signing the assignment) who is personally known to me, execute the above assignment.

[Signature] (signature of first witness)

Signed at 5th Floor, 1st Building, KIC Plaza, No. 252 Songhu Road, Shanghai, China (location of witness signature)

on this day 7.26 of 2018. (date of signature)

I Jin peng. Liu (name) whose residential address is

5th F, 1st Building, KIC Plaza, No. 252 Songhu Rd, SH China
was personally present and did see Pengfei Wu (name of person signing the assignment) who is personally known to me, execute the above assignment.

[Signature] (signature of second witness)

Signed at 5th F, 1st Building KIC Plaza, No. 252, Songhu Rd, SH China (location of witness signature)

on this day 7.26 of 2018. (date of signature)

Date: _____

Inventor's Signature

Print full name of second inventor: Stephen J. Todd
Residence: Center Conway, New Hampshire
Citizenship: United States of America
Mailing Address: 1857 White Mountain Highway, #301
North Conway, New Hampshire 03860

I _____ (name) whose residential address is

was personally present and did see Stephen J. Todd (name of person signing the assignment)
who is personally known to me, execute the above assignment.

_____ (signature of first witness)

Signed at _____ (location of witness signature)

on this day _____ of 20____. (date of signature)

I _____ (name) whose residential address is


was personally present and did see Stephen J. Todd (name of person signing the assignment)
who is personally known to me, execute the above assignment.

_____ (signature of second witness)

Signed at _____ (location of witness signature)

on this day _____ of 20____. (date of signature)

Date: 2012/7/27


Inventor's Signature

Print full name of third inventor: Kun Wang
Residence: Beijing, China
Citizenship: China
Mailing Address: No.288, Chaoyangmennei Dajie
Dongcheng District
Beijing, China 100010

I Bei Chen (name) whose residential address is

8/F, Building D, TSP, Zhongguancun East Road, Beijing P.R.C.
was personally present and did see Kun Wang (name of person signing the assignment) who is personally known to me, execute the above assignment.

Bei Chen (signature of first witness)

Signed at Beijing, 8/F, TSP (location of witness signature)

on this day July 27th of 2012 (date of signature)

I Mao Zou (name) whose residential address is

8/F, Building D, TSP, Zhongguancun East Road, Beijing P.R.C.
was personally present and did see Kun Wang (name of person signing the assignment) who is personally known to me, execute the above assignment.

Mao Zou (signature of second witness)

Signed at Beijing, 8/F, TSP (location of witness signature)

on this day July 27th of 2012 (date of signature)

ASSIGNMENT

WHEREAS, we, Pengfei Wu, Stephen J. Todd and Kun Wang, have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled **DECENTRALIZED POLICY PUBLISH AND QUERY SYSTEM FOR MULTI-CLOUD COMPUTING ENVIRONMENT**, the specification of which:

☐ is being executed on even date herewith and is about to be filed in the United States Patent Office;

☒ was filed on July 30, 2018 as U.S. Application No. 16/048,785;

☐ was patented under U.S. Patent No. _____ on _____.

WHEREAS, EMC IP Holding Company LLC (hereinafter "ASSIGNEE"), a limited liability company organized and existing under the laws of the State of Delaware and having a usual place of business at 176 South Street, Hopkinton, Massachusetts 01748 desires to acquire an interest therein in accordance with agreements duly entered into with us;

NOW, THEREFORE, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by us had this assignment and sale not been made; we hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. We hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

AND, we hereby further agree for ourselves and our executors and administrators to execute upon request any other lawful documents and likewise to perform any other lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of substitution,

reissue, divisional or continuation applications and preliminary or other statements and the giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

AND, we do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives.

IN TESTIMONY WHEREOF, we have hereunto set our hands and affixed our seals as set forth below:

Date: _____

Inventor's Signature

Print full name of first inventor: Pengfei Wu
Residence: Shanghai, China
Citizenship: China
Mailing Address: 5th Floor, 1st Building, KIC Plaza, No. 252
Songhu Road, Yangpu District
Shanghai, China 200433

I _____ (name) whose residential address is

was personally present and did see Pengfei Wu (name of person signing the assignment) who is personally known to me, execute the above assignment.

(signature of first witness)

Signed at _____ (location of witness signature)

on this day _____ of 20____. (date of signature)

I _____ (name) whose residential address is

was personally present and did see Pengfei Wu (name of person signing the assignment) who is personally known to me, execute the above assignment.

(signature of second witness)

Signed at _____ (location of witness signature)

on this day _____ of 20____. (date of signature)

Date: AUG 12 2018

Stephen J. Todd
Inventor's Signature

Print full name of second inventor: Stephen J. Todd
Residence: Center Conway, New Hampshire
Citizenship: United States of America
Mailing Address: 1857 White Mountain Highway, #301
North Conway, New Hampshire 03860

I THOMAS HOLT (name) whose residential address is

28 Cottage Rd Dudley MA
was personally present and did see Stephen J. Todd (name of person signing the assignment)
who is personally known to me, execute the above assignment.

J. Holt (signature of first witness)

Signed at 28 Cottage Rd Dudley MA (location of witness signature)

on this day AUG 12 of 2018. (date of signature)

I Pamela Holt (name) whose residential address is

28 Cottage Rd Dudley MA
was personally present and did see Stephen J. Todd (name of person signing the assignment)
who is personally known to me, execute the above assignment.

Pamela Holt (signature of second witness)

Signed at 28 Cottage Rd Dudley MA (location of witness signature)

on this day AUG 12 of 2018. (date of signature)

Date: _____

Inventor's Signature

Print full name of third inventor: Kun Wang
Residence: Beijing, China
Citizenship: China
Mailing Address: No.288, Chaoyangmennei Dajie
Dongcheng District
Beijing, China 100010

I _____ (name) whose residential address is

was personally present and did see Kun Wang (name of person signing the assignment) who is personally known to me, execute the above assignment.

(signature of first witness)

Signed at _____ (location of witness signature)

on this day _____ of 20____. (date of signature)

I _____ (name) whose residential address is

was personally present and did see Kun Wang (name of person signing the assignment) who is personally known to me, execute the above assignment.

(signature of second witness)

Signed at _____ (location of witness signature)

on this day _____ of 20____. (date of signature)